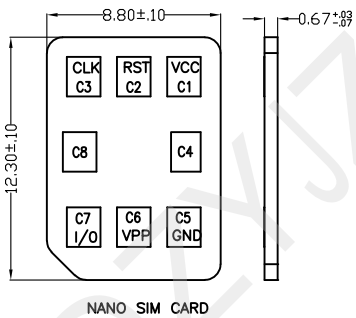
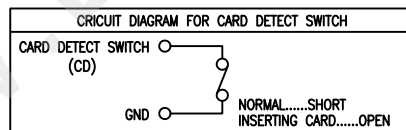


RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

PAD
 KEEP OUT AREA



NANO SIM CARD



SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

NOTES:

- 1) MATERIAL:
 - HOUSING: HI-TEMP. PLASIC UL 94V-0
 - CONTACT: COPPER ALLOY
 - SHELL: STAINLESS STEEL
- 2) PLATING:
 - TERMINAL:
 - CONTACT AREA: Au GOLD FLASH.
 - SOLDER AREA: AU GOLD FLASH.
 - UNDER PLATE: NICKEL.
 - SHELL: NICKEL PLATED OVER ALL.
 - SOLDER AREA: GOLD FLASH.
3. SPECIALITY:
 - 3.1 Rated current: 1.0A
 - 3.2 Rated voltage: 30V
 - 3.3 Contact Resistance: 100mΩ MAX
 - 3.4 Insulation Resistance: 1000MΩ MIN 500V DC
 - 3.5 Dielectric withstanding voltage: 500V AC.
 - 3.6 Solder ability: 260±0/-5°C, 30±10s.
 - 3.7 Durability: 5000 Cycles Min.
 - 3.8 Operating condition: Temperature -40°C ~ +85°C;
Humidity 80% R.H MAX



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X: ±2' X.X' ±0.5'	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: NANO SIM PUSH 1.37H 带CD PIN 无柱
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC388-SIM07-137 MOLD NO.
UNIT: mm [inch] SCALE: 1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO: HYC-2603231030 SHEET NO. 1 OF 1